

H&M502 (双工位)

Single station Low pressure molding machine

应用范围

适用于各式低压热熔胶成型树脂对产品注胶封装；其制程压力低 0-6Mpa，不损伤零部件，无化学反应，快速成形。可取代灌封胶与外壳，成形后有保护，绝缘与防水效果。广泛应用于：各类汽车电子与汽车线束、同轴线缆、防水接插件、LED 模块与串灯、PCBA 模块、传感器、线圈、软性电路板、聚合物电池、智能家居、可穿戴电子产品的批量生产。

Application scope

Suitable for product coating by all kinds of low pressure molding hot-melt adhesive resin; The working pressure from 0 to 6 Mpa, It won't damage parts, have no chemical reaction, rapid prototyping, and can replace the pouring sealant with shell. After forming protection, It has insulation and waterproof effect. KONIG Low pressure injection molding solution is Mainly applied to bulk-production of Automotive Electronics and automotive wiring harness, coaxial cable, waterproof connectors, LED modules and lamps, PCBA, sensors, coil, soft circuit boards, polymer battery, smart home, wearable electronic.

设备特点

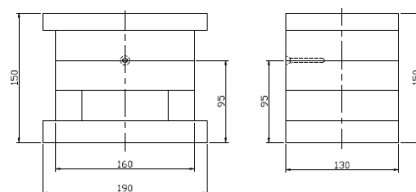
1. 注胶系统采用最新超硬齿轮泵和注胶枪，结构紧凑，注胶稳定，使用寿命长。
2. 双工位、双枪侧式注胶，对较复杂的多模穴与滑块机构的模具应用给予较大的应用空间。
3. 注胶压力大小可通过面板压力调节阀进行调节。
4. 操作台和熔胶系统采用分体布局，使用灵活。
5. 机台分五段控温，胶缸、胶管和胶枪均可独立控制，温度控制精准。
6. 工作保护采用双手操作、同时配备红外线光幕保护开关。
7. 模架采用标准设计更容易互换,工作台设有产品顶出装置。方便产品从模具中取出。
8. 可选配双胶缸，注胶更稳定，生产效率更高，应用更广泛。

Features

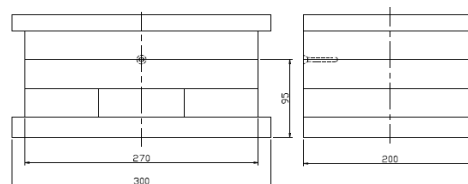
1. Injection system using the latest super hard gear pump and glue guns, it has compact structure, injecting stability, long service life.
2. Double position and double horizontal glue gun, providing larger application space for more complex mould.
3. Injecting pressure can be adjusted through the control panel.
4. Work station and melt system adopts fission layout and uses flexible.
5. Three temperature controllers for all system components (glue gun, heated hose, Melt tank), controls the temperature accurately.
6. Using double hands for working, and equipping with infrared light curtain protection switch.
7. Mould with a standard design, easy mold-set change, and equipped with product ejection device for removing product from the mould convenient.
8. Optional double glue cylinder, more stable injection, higher effective production and used more widely.

机器参数 Specification

机台尺寸重量	Machine Size	1080mmX720mmX1890mm (446Kgs)
包装尺寸重量	Packing Size	1280mmX920mmX2000mm (496Kgs)
工作台高度	Work Station Height	1030mm
熔胶系统型号与数量	Melting Tank Model &Q'ty	KH05 (5Liter)X1PC



标准模架 Standard mold set



最大模架 Max mold set

注胶枪型号与数量角度	Nozzle & Tip Angle	KG40X2PC(36°)
注胶管型号与数量	Heated Hose Model &Q'ty	KJ16X2PC
输入电压	Electricity	220VAC/1Phase/50 or 60Hz
温控分区	Temperature Control Zones	5
最高设定温度	Temperature Range Ambient	up to 250°C
最大功率	Max. Power	4.5Kw
最低工作气压	Min. Air Pressure	0.5Mpa
用气量	Air Consumption	0.1m³/min
合模方式	Clamping Device	气缸(Cylinder)
合模压力	Clamping Force	Max.1.2Ton
合模行程	Clamping Stroke (mm)	150mm
控制系统	Control System	PLC+7" HMI
标准模具尺寸 (mm)	LPIM Standard Mold Set Size (mm)	190X130X150
模具最大尺寸	Max. Mold Set Size (mm)	300X200X150

